Tyrone Camarero Specifications



Camerero: SDI300C2R-18

Key Feature

1U Hyper with 8 hot-swap 2.5" NVMe/SAS/SATA bays and 3 PCIe 5.0 x16 + 1 PCIe 5.0 x16 AIOM slot Virtualization, Software-defined Storage, High Performance Computing, Cloud Computing, Enterprise Server

- "Dual Socket E2 (LGA-4710), Intel® Xeon® 6 6700 series processors with E-cores,Up to 144C/144T; Up to 108MB Cache per CPU

 Note: Supports up to 330W TDP CPUs (Air Cooled)*, Supports up to 330W TDP CPUs (Liquid Cooled),
- *Air Cooled CPUs with TDP over 250W only supported under specific conditions. Contact a Tyrone representative for details."
- "32 DIMM slots supporting up to 4TB of memory, Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM,
- Max Memory (2DPC): Up to 4TB 5200MT/s ECC DDR5 RDIMM"
- 1 PCle 5.0 x16 FHHL slot, 2 PCle 5.0 x16 FH/10.5"L slots, 1 PCle 5.0 x16 AIOM slot (OCP 3.0 compatible)
- Flexible networking options with 1 AIOM networking slot (OCP NIC 3.0 compatible)
- 8x 2.5" hot-swap NVMe/SATA/SAS drive bays; Optional 4x 2.5" hot-swap NVMe/SAS/SATA drive bays; 2x internal M.2 NVMe drive slots; Optional RAID support via storage add-on card
- "Fans: 8 counter-rotating 40x40x56mm Fan(s)
- Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)"
- 2x 1200W/1600W/2000W/2600W Redundant (1 + 1) Titanium Level (96%) power supplies





Processor/Cache

Processor

Dual Socket E2 (LGA-4710), Intel® Xeon® 6 6700 series processors with E-cores, Up to 144C/144T; Up to 108MB Cache per CPU Note: Supports up to 330W TDP CPUs (Air Cooled)*, Supports up to 330W TDP CPUs (Liquid Cooled),

*Air Cooled CPUs with TDP over 250W only supported under specific conditions. Contact a Tyrone representative for details.

Chipset

Chipset System on Chip

System Memory

Memory Capacity

"32 DIMM slots supporting up to 4TB of memory, Max Memory (1DPC): Up to 2TB

6400MT/s ECC DDR5 RDIMM,

Max Memory (2DPC): Up to 4TB 5200MT/s

ECC DDR5 RDIMM"

Expansion Slot

PCI-Express 1 PCIe 5.0 x16 FHHL slot, 2 PCIe 5.0 x16

FH/10.5"L slots, 1 PCIe 5.0 x16 AIOM slot

(OCP 3.0 compatible)

Integrated Onboard

NVMe; RAID 0/1/5/10 support(Intel®

VROC RAID key required)

LAN 1 RJ45 1 GbE Dedicated BMC LAN port(s)

Add-on Options

Raid Card Optional

Optical None

Drive

Drive bays

HDD Bays

Default: Total 8 bays 8 front hot-swap 2.5"

NVMe*/SAS*/SATA* drive bays

Option A: Total 12 bays 12 front hot-swap 2.5""

NVMe*/SAS*/SATA* drive bays

Power Supply

Power Supply

2x 1200W/1600W/2000W/2600W

Redundant (1 + 1) Titanium Level (96%)

power supplies

Cooling System

Fans

8 counter-rotating 40x40x56mm Fan(s)

Liquid Cooling

Direct to Chip (D2C) Cold Plate

(optional)

Form Factor

Form Factor

2U Rackmount

Dimensions

Dimensions

1.71" (43.6 mm), Width: 17.3" (438.4

mm), Depth: 29.27" (743.38 mm)

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